

FFKM Compound QFF-H170 and QFF-H180

Product Description

Composition	FFKM Compound
Features	Excellent processability, resistant to almost all solvents including ketones and esters
Typical uses	O-rings, gaskets, etc.
Processing technology	Compression molding
Curing system	peroxide
Using Temperature	-10°C-230°C

Properties	Typical Value	
	QFF-H170	QFF-H180
Density	2.2	2.3
Color	Black	Black
Solubility	practically insoluble in any solvent	

Typical Curing Properties

Monsanto Moving Die Rheometer (MDR2000®)

100cpm, 0.5°Arc, 15 minutes, 155°C

ML, Min. Torque, dNm	1.50	1.90
ts ₂ ,	1'42"	1'43"
t' 90,	8'26"	8'29"
MH, Max. Torque, dNm	22.01	24.10

Typical Physical Properties

Press curing at 155°C for 15 minutes

Over curing at 230°C for 4 hours

Tensile Strength (ASTM D412), Mpa	15	16.5
Elongation (ASTM D412), %	140	130
Hardness (ASTM D2240), Shore A	70	80

Compression Rate, [ASTM D395 Method B (Disc)]

70h @ 200°C, %	24
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